

➤ Features

- Size 0.12*0.10 inch /3.2*2.5 mm
- RoHS compliant, lead-free and halogen-free
- Fast response to fault current
- Low resistance
- Low profile
- Compatible with high temperature solders

➤ Applications

- Computer, Mobile phones, Multimedia
- Automotive, Industrial controls, Telephony and broadband
- Game machines, Portable electronics, Battery

➤ Electrical Characteristics (25°C)

Part Number	I_{hold}	I_{trip}	V_{max}	I_{max}	$P_{d\ typ}$	Time to trip		R_i	R_{1max}
	(A)	(A)	(V _{dc})	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)
BSMD1210L-150	1.50	3.0	6.0	50	1.2	8.0	0.5	0.005	0.050
BSMD1210L-175	1.75	3.5	6.0	50	1.2	8.0	1.0	0.005	0.045
BSMD1210L-190	1.90	3.8	6.0	50	1.2	8.0	3.0	0.005	0.042
BSMD1210L-200	2.00	4.0	6.0	50	1.2	8.0	3.0	0.004	0.040
BSMD1210L-210	2.10	4.2	6.0	50	1.2	8.0	5.0	0.004	0.035
BSMD1210L-230	2.30	4.6	6.0	50	1.2	8.0	5.0	0.004	0.032
BSMD1210L-250	2.50	5.0	6.0	50	1.2	8.0	5.0	0.003	0.030
BSMD1210L-260	2.60	5.2	6.0	50	1.2	12.0	5.0	0.003	0.028
BSMD1210L-300	3.00	6.0	6.0	50	1.2	12.0	5.0	0.003	0.026
BSMD1210L-350	3.50	7.0	6.0	50	1.2	12.0	5.0	0.002	0.024
BSMD1210L-380	3.80	7.6	6.0	50	1.5	12.0	5.0	0.002	0.020
BSMD1210L-400	4.00	8.0	6.0	50	1.5	16.0	5.0	0.001	0.018
BSMD1210L-450	4.50	9.0	6.0	50	1.5	16.0	5.0	0.001	0.014
BSMD1210L-500	5.00	10.0	6.0	50	1.5	16.0	5.0	0.001	0.012
BSMD1210L-550	5.50	11.0	6.0	50	1.5	20.0	5.0	0.0008	0.010
BSMD1210L-600	6.00	12.0	6.0	50	1.5	20.0	5.0	0.0008	0.009
BSMD1210L-650	6.50	13.0	6.0	50	1.5	20.0	5.0	0.0005	0.008
BSMD1210L-700	7.00	14.0	6.0	50	1.6	20.0	5.0	0.0005	0.008
BSMD1210L-750	7.50	15.0	6.0	50	1.6	20.0	5.0	0.0005	0.007
BSMD1210L-800	8.00	16.0	6.0	50	1.6	20.0	5.0	0.0004	0.007
BSMD1210L-850	8.50	17.0	6.0	50	1.6	20.0	5.0	0.0004	0.006
BSMD1210L-900	9.00	18.0	6.0	50	1.6	30.0	5.0	0.0003	0.006

Part Number	I_{hold}	I_{trip}	V_{max}	I_{max}	$P_{d\ typ}$	Time to trip		R_i	R_{1max}
	(A)	(A)	(V _{dc})	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)
BSMD1210L-950	9.50	19.0	6.0	50	1.6	30.0	5.0	0.0002	0.006
BSMD1210L-1000	10.00	20.0	6.0	50	1.6	30.0	5.0	0.0002	0.005
BSMD1210L-1050	10.50	21.0	6.0	50	1.8	30.0	5.0	0.0002	0.005
BSMD1210L-1100	11.00	22.0	6.0	50	1.8	30.0	5.0	0.0001	0.0045
BSMD1210L-1150	11.5	23.0	6.0	50	1.8	30.0	5.0	0.0001	0.0045
BSMD1210L-1200	12.0	24.0	6.0	50	1.8	30.0	5.0	0.0001	0.004

I_{hold} = Hold current: maximum current device will pass without tripping in 25°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 25°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max}).

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).

$P_{d\ typ.}$ = Typical power dissipated from device when in the tripped state at 25°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Caution: Operation beyond the specified ratings may result in damage and possible arcing and flame.

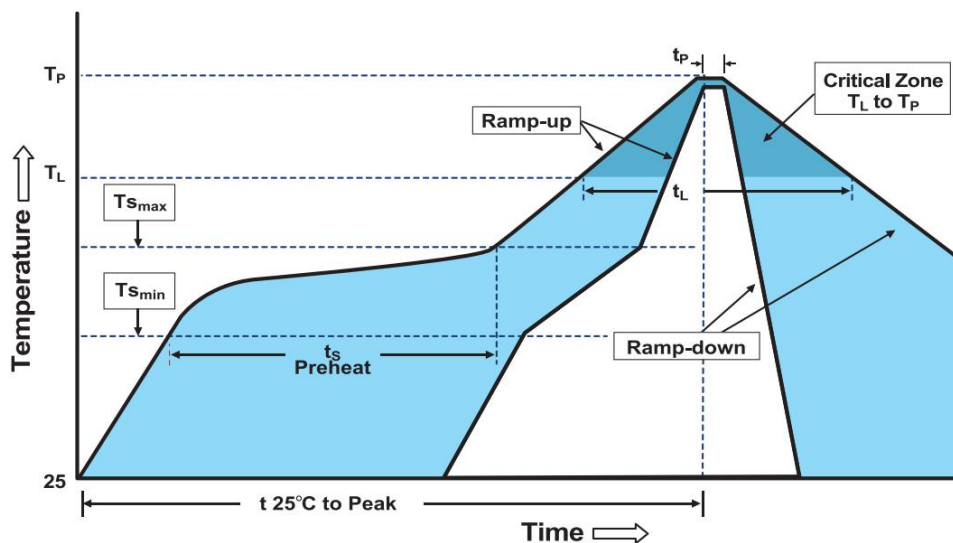
➤ WARNING

- Users shall independently assess the suitability of these devices for each of their applications.
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire.
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration.
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the prolonged of these PPTC devices.
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses.
- Circuits with inductance may generate a voltage ($L\ di/dt$) above the rated voltage of the PPTC device.

➤ Thermal Derating Chart

Part Number	Ambient operating temperature hold current(I_{hold})							
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C
BSMD1210L-150	2.3	2.0	1.7	1.5	1.3	1.2	1.1	0.9
BSMD1210L-175	2.6	2.3	2.0	1.75	1.5	1.3	1.2	1.1
BSMD1210L-190	2.9	2.5	2.2	1.9	1.6	1.5	1.3	1.2
BSMD1210L-200	3.0	2.7	2.3	2.0	1.7	1.5	1.4	1.2
BSMD1210L-210	3.2	2.8	2.4	2.1	1.8	1.6	1.5	1.3
BSMD1210L-230	3.5	3.1	2.7	2.3	2.0	1.8	1.6	1.4
BSMD1210L-250	3.8	3.3	2.9	2.5	2.2	1.9	1.8	1.5
BSMD1210L-260	3.9	3.5	3.0	2.6	2.2	2.0	1.9	1.6
BSMD1210L-300	4.5	4.0	3.5	3.0	2.6	2.3	2.1	1.8
BSMD1210L-350	5.3	4.7	4.1	3.5	3.0	2.7	2.5	2.1
BSMD1210L-380	5.7	5.1	4.4	3.8	3.3	2.9	2.7	2.3
BSMD1210L-400	6.0	5.3	4.6	4.0	3.4	3.1	2.8	2.4
BSMD1210L-450	6.8	6.0	5.2	4.5	3.9	3.5	3.2	2.7
BSMD1210L-500	7.5	6.7	5.8	5.0	4.3	3.9	3.5	3.1
BSMD1210L-550	8.3	7.3	6.4	5.5	4.7	4.2	3.9	3.4
BSMD1210L-600	9.0	8.0	7.0	6.0	5.2	4.6	4.2	3.7
BSMD1210L-650	9.8	8.6	7.5	6.5	5.6	5.0	4.6	4.0
BSMD1210L-700	11.3	9.8	8.3	7.0	6.4	5.3	4.9	4.5
BSMD1210L-750	12.0	10.4	8.8	7.5	7.2	5.6	5.2	4.8
BSMD1210L-800	12.8	11.1	9.4	8.0	7.5	6.0	5.5	5.1
BSMD1210L-850	13.5	11.7	9.9	8.5	8.1	6.3	5.9	5.4
BSMD1210L-900	14.3	12.4	10.5	9.0	8.6	6.7	6.2	5.7
BSMD1210L-950	15.0	13.0	11.0	9.5	9.0	7.0	6.5	6.0
BSMD1210L-1000	15.8	13.7	11.6	10.0	9.5	7.4	6.8	6.3
BSMD1210L-1050	16.5	14.3	12.1	10.5	9.9	7.7	7.2	6.6
BSMD1210L-1100	17.3	15.0	12.7	11.0	10.4	8.1	7.5	6.9
BSMD1210L-1200	18.8	16.3	13.8	12.0	11.3	8.8	8.1	7.5

➤ **Soldering Parameters**



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate(T_{smax} to T_P)	3°C/second max
Preheat	
-Temperature Min(T_{smin})	150°C
-Temperature Max(T_{smax})	200°C
-Time(T_{smin} to T_{smax})	60~180 seconds
Time maintained above:	
-Temperature(T_L)	217°C
-Time(t_L)	60~150 seconds
Peak Temperature(T_P)	260°C
Ramp-Down Rate	6°C/second max
Time 25°C to Peak Temperature	8 minutes max
Storage Condition	0°C~30°C,30%-60%RH

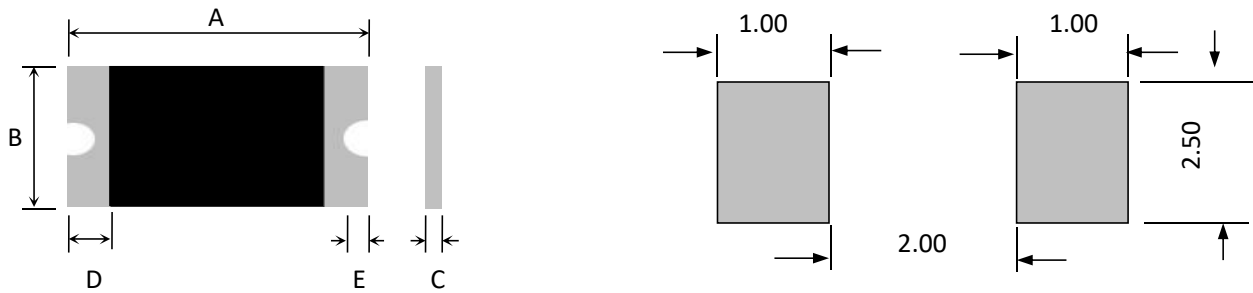
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead-free.
- Recommended maximum paste thickness is 0.25mm.
- Devices can be cleaned using standard industry methods and solvents.

Note 1: All temperature refer to topside of the package, measured on the package body surface.

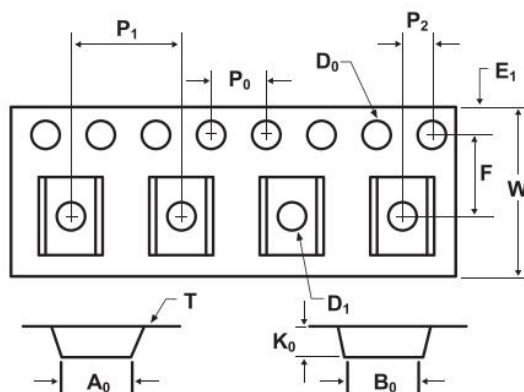
Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

➤ **Environmental Specifications**

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

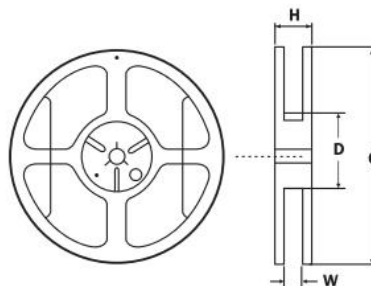
➤ Physical Dimensions & Recommended Pad Layout (mm)


Part Number	Quantity	A		B		C		D	E
		Min	Max	Min	Max	Min	Max	Min	Min
BSMD1210L-150	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-175	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-190	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-200	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-210	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-230	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-250	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-260	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-300	4000	--	3.50	--	2.85	--	0.8	0.25	0.10
BSMD1210L-350	4000	--	3.50	--	2.85	--	1.0	0.25	0.10
BSMD1210L-380	4000	--	3.50	--	2.85	--	1.0	0.25	0.10
BSMD1210L-400	4000	--	3.50	--	2.85	--	1.0	0.25	0.10
BSMD1210L-450	4000	--	3.50	--	2.85	--	1.0	0.25	0.10
BSMD1210L-500	4000	--	3.50	--	2.85	--	1.0	0.25	0.10
BSMD1210L-550	4000	--	3.50	--	2.85	--	1.0	0.25	0.10
BSMD1210L-600	4000	--	3.50	--	2.85	--	1.1	0.25	0.10
BSMD1210L-650	3000	--	3.50	--	2.85	--	1.2	0.25	0.10
BSMD1210L-700	3000	--	3.50	--	2.85	--	1.2	0.25	0.10
BSMD1210L-750	3000	--	3.50	--	2.85	--	1.2	0.25	0.10
BSMD1210L-800	3000	--	3.50	--	2.85	--	1.2	0.25	0.10
BSMD1210L-850	3000	--	3.50	--	2.85	--	1.2	0.25	0.10
BSMD1210L-900	3000	--	3.50	--	2.85	--	1.4	0.25	0.10
BSMD1210L-950	3000	--	3.50	--	2.85	--	1.4	0.25	0.10
BSMD1210L-1000	3000	--	3.50	--	2.85	--	1.4	0.25	0.10
BSMD1210L-1050	3000	--	3.50	--	2.85	--	1.6	0.25	0.10
BSMD1210L-1100	3000	--	3.50	--	2.85	--	1.6	0.25	0.10
BSMD1210L-1150	3000	--	3.50	--	2.85	--	1.6	0.25	0.10
BSMD1210L-1200	3000	--	3.50	--	2.85	--	1.6	0.25	0.10

➤ Tape And Reel Specifications (mm)


Governing Specifications	BSMD1210L-150~ BSMD1210L-380	BSMD1210L-400~ BSMD1210L-600	BSMD1210L-650~ BSMD1210L-1200
W	8.0 ± 0.3	8.0 ± 0.3	8.0 ± 0.3
F	3.5 ± 0.05	3.5 ± 0.05	3.5 ± 0.05
E1	1.75 ± 0.1	1.75 ± 0.1	1.75 ± 0.1
D0	1.55 ± 0.05	1.55 ± 0.05	1.55 ± 0.05
D1	1.0 ± 0.1	1.0 ± 0.1	1.0 ± 0.1
P0	4.0 ± 0.1	4.0 ± 0.1	4.0 ± 0.1
P1	4.0 ± 0.1	4.0 ± 0.1	4.0 ± 0.1
P2	2.0 ± 0.05	2.0 ± 0.05	2.0 ± 0.05
A0	2.9 ± 0.1	2.9 ± 0.1	2.9 ± 0.1
B0	3.65 ± 0.1	3.65 ± 0.1	3.65 ± 0.1
T	0.2 ± 0.1	0.2 ± 0.1	0.2 ± 0.1
K0	0.74 ± 0.1	1.04 ± 0.1	1.35 ± 0.1
Leader min	390	390	390
Trailer min	160	160	160

Reel Dimensions	
C	φ178 ± 1.0
D	φ60.2 ± 0.5
H	11.0 ± 0.5
W	9.0 ± 1.5


➤ Contact information
SHENZHEN HCHC ELECTRONIC CO., LTD
TEL: 0755-85259917 FAX: 0755-28704432
E-MAIL: sale@hchc-elec.com